

II. Remarks

This Second Preliminary Amendment and Response to Notice of Non-Compliant Amendment is filed in response to a Notice of Non-Compliant Amendment mailed August 29, 2007. In the Notice of Non-Compliant Amendment, it was pointed out that the status identifier for claims 12 through 19 was mistakenly noted as being "previously withdrawn." Upon further review of the File Wrapper for the present patent application, applicants' attorney observes that claims 12 through 19 were indicated as being "canceled" in an Amendment filed March 12, 2007. Applicants' attorney thanks the Legal Instruments Examiner for discovering this error, and apologizes for the error. Accordingly, in the Listing of Claims presented in this Second Preliminary Amendment and Response to Notice of Non-Compliant Amendment, the status of claims 12 through 19 is now properly indicated as that of "cancelled," thereby curing the deficiencies cited in the Notice of Non-Compliant Amendment.

U.S. Patent Appln. Ser. No. 10/807,417 entitled "Microcap Wafer Bonding Apparatus" to Fazzio; Avago Technologies Attorney Docket No. 10030899-1; Woods Patent Law Docket No. P AVG 188.

III. Summary

For the reasons set forth in the Preliminary Amendment and Response filed August 27, 2007, new claims 24-36 are pending in the present application, and are believed to be in condition for allowance. Examination of the application as amended is requested. The Examiner is respectfully requested to contact the undersigned by telephone or e-mail with any questions or comments she may have.

Respectfully submitted,
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